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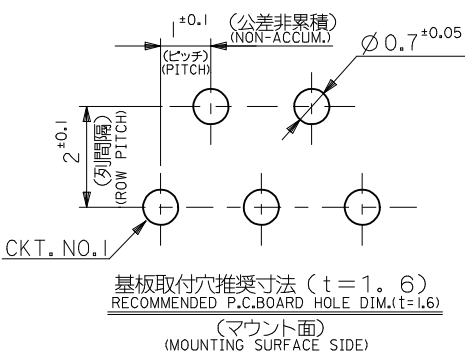
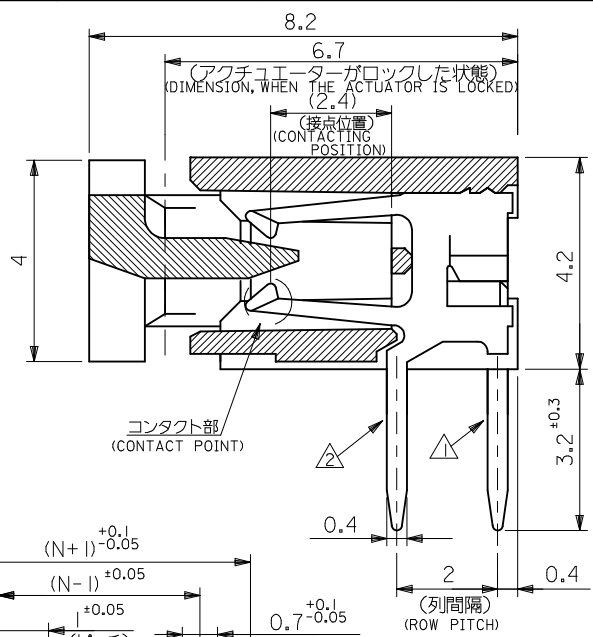
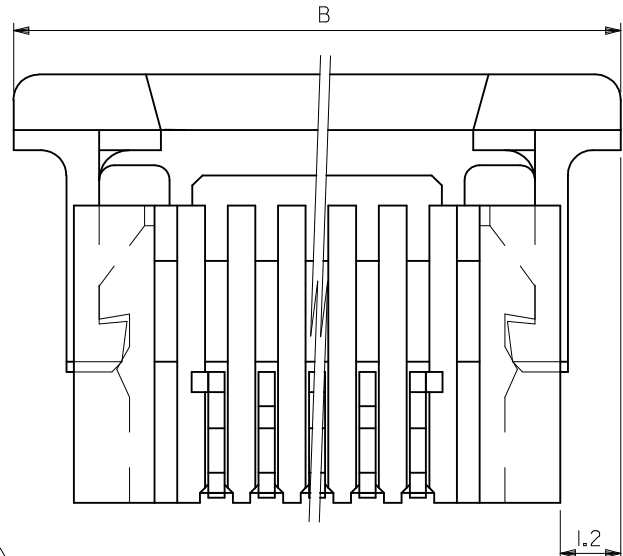
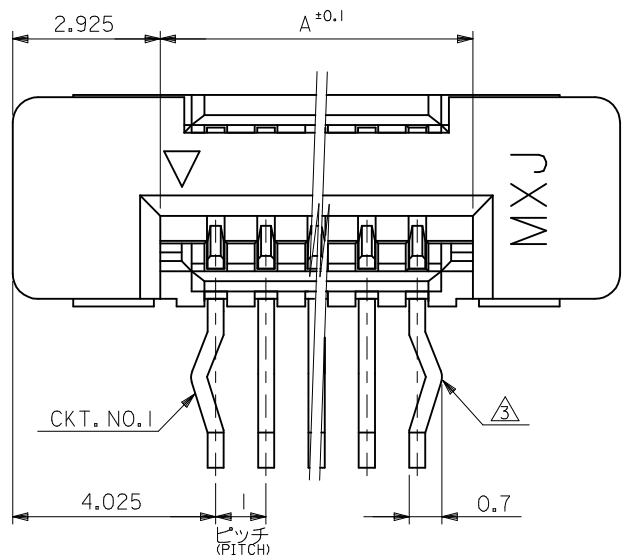
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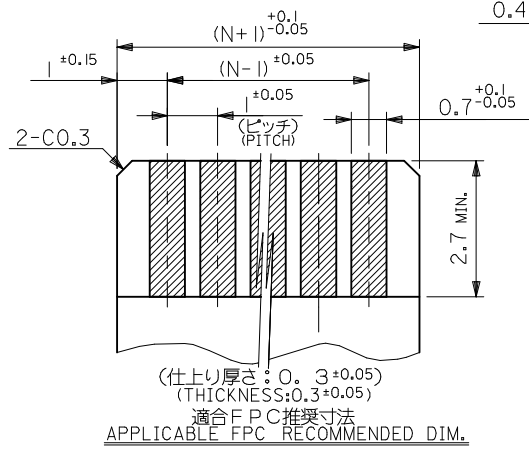
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基板取付穴推奨寸法 (t=1.6)  
RECOMMENDED P.C. BOARD HOLE DIM.(t=1.6)  
(マウント面)  
(MOUNTING SURFACE SIDE)



(仕上り厚さ: 0.3±0.05)  
(THICKNESS: 0.3±0.05)  
適合FPC推奨寸法  
APPLICABLE FPC RECOMMENDED DIM.

FPCについて:  
打抜き方向は導体側から補強板を推奨致します。補強フィルム材質はポリアイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。  
ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT :  
THERMOSETTING BONDING AGENT

- 注記:  
NOTES:
- ① CKT. NO. 1を基準に偶数番目のソルダータール。  
EVEN NUMBER SOLDER TAIL.
  - ② CKT. NO. 1を基準に奇数番目のソルダータール。  
ODD NUMBER SOLDER TAIL.
  - ③ ソルダータールキップは、△のソルダータールの両端部に設ける。  
KINK TO BE APPLIED FOR THE BOTH END OF ODD NUMBER SOLDER TAIL
4. 材 料: ターミナル:リン青銅、ニッケル下地 銅ビスマスマスメッキ (t=0.32)  
MATERIAL: TERMINAL:PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING (t=0.32)  
ハウジング: 66ナイロン, UL94V-0  
HOUSING: 66NYLON,UL94V-0  
アクチュエーター: ポリエステル, UL94V-0  
ACTUATOR: POLYESTER,UL94V-0
5. 本製品は 52043-\*\*-10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52043-\*\*-10.

11.05	5.2	52043-0419	4
B	A	MATERIAL NO.	極数 CKT.
MODEL NO.		52043-**-19	

REVISED EC NO: J2017-0269 DRWNGS CHKD: APPR:MSASAO	DESCRIPTION 2016/11/17 2016/12/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	UNDER	±	DRAWN BY YWADA	DATE 2004/05/19	TITLE 1.0 FPC CONN. Z.I.F R/A			
		0.25 OVER	0.5 UNDER	±	CHECKED BY MSASAO	DATE 2004/05/19	-LEAD FREE- <b>molex</b>			
		0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE				
0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52043-002		SHEET NO. 1 OF 1			
10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

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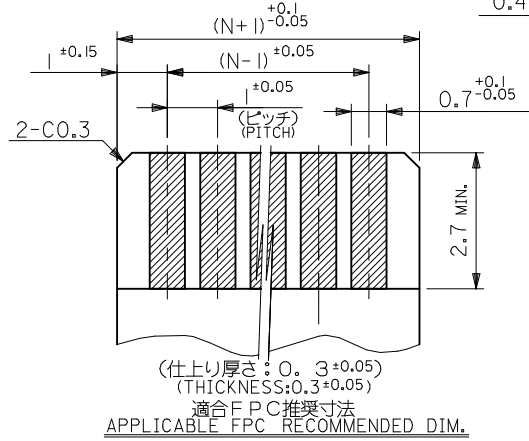
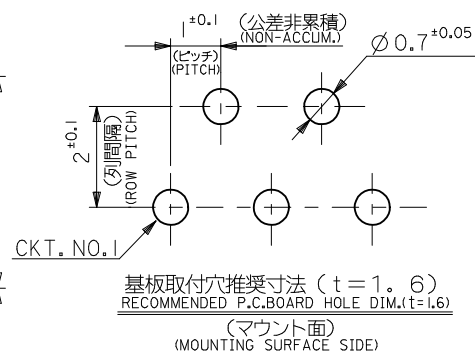
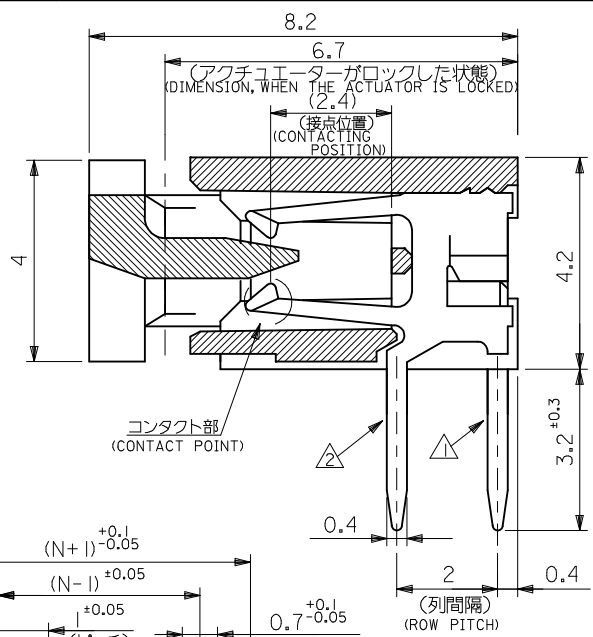
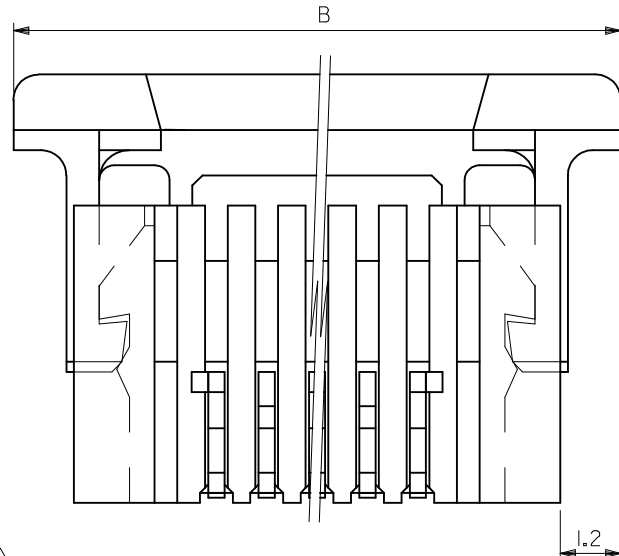
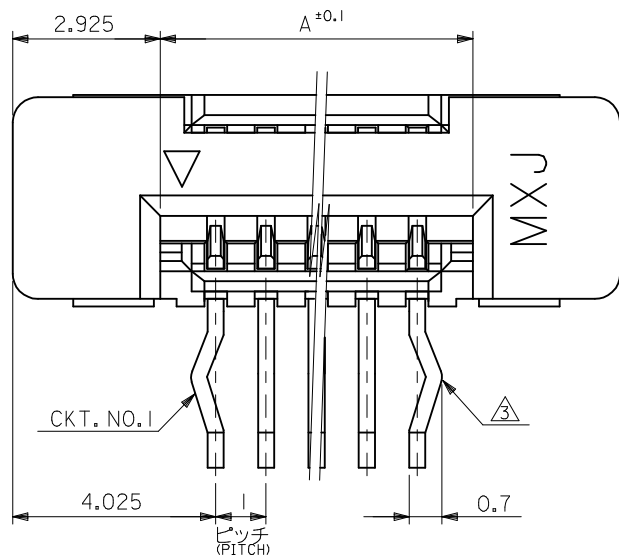
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FPCについて:  
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 接着剤は熱硬化接着剤を推奨致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT :  
 THERMOSETTING BONDING AGENT

- 注記:  
 NOTES: ① C.K.T. NO. 1を基準に偶数番目のソルダータール。EVEN NUMBER SOLDER TAIL.  
 ② C.K.T. NO. 1を基準に奇数番目のソルダータール。ODD NUMBER SOLDER TAIL.  
 ③ ソルダータールキップは、△のソルダータールの両端部に設ける。KINK TO BE APPLIED FOR THE BOTH END OF ODD NUMBER SOLDER TAIL.  
 4. 材 料: ターミナル:リン青銅、ニッケル下地 銅ビスマスマスメッキ (t=0.32)  
 MATERIAL: TERMINAL:PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING (t=0.32)  
 ハウジング: 66ナイロン, UL94V-0  
 HOUSING: 66NYLON,UL94V-0  
 アクチュエーター: ポリエステル, UL94V-0  
 ACTUATOR: POLYESTER,UL94V-0  
 5. 本製品は 52043-\*\*10 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 52043-\*\*10.

11.05	5.2	52043-0419	4
B	A	MATERIAL NO.	極数 C.K.T.
MODEL NO.		52043-**19	

REVISED EC NO: J2017-0269 DRWNGS CHKD: APPR:MSASAO	DESCRIPTION 2016/11/17 2016/12/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	UNDER	±	DRAWN BY YWADA	DATE 2004/05/19	TITLE 1.0 FPC CONN. Z.I.F R/A			
		0.25 OVER	0.5 UNDER	±	CHECKED BY MSASAO	DATE 2004/05/19	-LEAD FREE- <b>molex</b>			
		0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE				
0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52043-002		SHEET NO. 1 OF 1			
10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							